

ADHESIVE FILM FOR WAFER PROCESSING

ABSTRACT

Disclosed is an adhesive film for wafer processing, which
5 has a prevention effect of semiconductor chips from colliding
during wafer processing. The adhesive film for the wafer
processing according to the disclosure includes a multi-layered
substrate; and a first adhesive layer disposed on a top surface
of the multi-layered substrate, the multi-layered substrate
10 having a sandwich structure in which a second adhesive layer is
interposed between an upper substrate layer and a lower substrate
layer.

[Fig. 1]

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